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(Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		248232US2S		New Application			
				APPLICANT					
LIST OF	REFER	ENCES CITED BY APP	LICANT	Kazuyuki HIGASHI, et al.					
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U.S. PATENT DOCUMENTS									
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OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)									
	AW	Norio OKADA, et al., "THERMAL STRESS OF 140nm-WIDTH Cu DAMASCENE INTERCONNECTS", Proceedings of the International Interconnect Technology Conference, 2002, pgs. 136 - 138.							
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	AZ	Additional References sheet(s) attached							
Examiner	W	YA A				Date Considered 5/21///			
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*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.									